ASU Ira A. Fulton Schools of Engineering
Arizona State University

ASU Professional Development Series

Future Frontiers: How AI will shape the Next Decade of Packaging

Date: August 13, 2025 | **Time:** 10am to 11am MST

Explore how advanced semiconductor packaging is powering cutting-edge AI applications, including Nvidia’s AI chips for data centers. Gain insights into how AI technologies, in turn, are helping to innovate packaging methods. This session will offer a forward-looking view of the evolving relationship between AI and packaging technologies.

Register now

Meet The Speakers:

Dr. Hongbin Yu

Professor at ASU
Ira A. Fulton Schools
of Engineering

Dr. Christopher Bailey

Professor at ASU
Ira A. Fulton Schools
of Engineering

For further questions please contact us at exec-fseonline@asu.edu.

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